

SDM035PU02S

-20V P-Channel MOSFETs

Rev 1.0

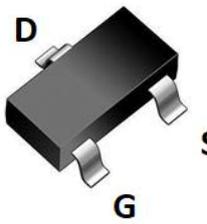
Feature

- ◇ Low $R_{DS(ON)}$
- ◇ Low Gate Charge
- ◇ High current Capability
- ◇ Green product RoHS compliant, lead free
- ◇ 100% UIS Tested, 100% Rg Tested

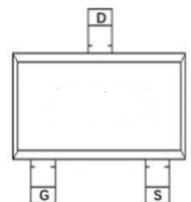
Product Summary

| | | |
|--|------|------------|
| V_{DS} | -20 | V |
| $V_{GS(th_Typ)}$ | -0.7 | V |
| $R_{DS(ON_Typ)}$ (@ $V_{GS} = -10V$) | 31 | m Ω |
| I_D (at $V_{GS} = -10V$) ⁽¹⁾ | -4.2 | A |

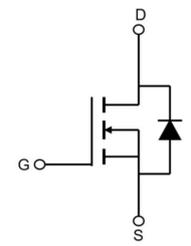
| Type | Package | Marking | Outline | Media | Quantity (pcs) |
|-------------|---------|---------|---------|---------|----------------|
| SDM035PU02S | SOT-23 | 2305 | Tape | 7" Reel | 3000 |



SOT-23 top view



Pin Assignment



Schematic Diagram

Absolute Maximum Ratings (Rating at $T_J=25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Maximum | Unit |
|---|----------------|-------------------|------------|
| Drain-Source Voltage | V_{DS} | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | V |
| Continuous Drain Current ⁽¹⁾ | I_D | $T_c=25^\circ C$ | -4.2 |
| | | $T_c=100^\circ C$ | -2.7 |
| Pulsed Drain Current ⁽²⁾ | I_{DM} | -17 | A |
| Body-Diode Continuous Current | I_S | -4.2 | A |
| Avalanche Current ⁽³⁾ | I_{AS} | -6.5 | A |
| Avalanche Energy ⁽³⁾ | E_{AS} | 4.9 | mJ |
| Power Dissipation ⁽⁴⁾ | P_D | $T_c=25^\circ C$ | 2 |
| | | $T_c=100^\circ C$ | 1 |
| Junction and Storage Temperature Range | T_J, T_{STG} | -55 to +150 | $^\circ C$ |

Electrical Characteristics (Rating at $T_J=25^\circ\text{C}$ unless otherwise noted)

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|--|------------------------------------|--|------|------|-----------|---------------|
| STATIC PARAMETERS | | | | | | |
| BV_{DSS} | Drain-Source Breakdown Voltage | $I_D=-250\mu\text{A}$, $V_{GS}=0\text{V}$ | -20 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=-20\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$ | - | - | -1 -5 | μA |
| I_{GSS} | Gate-Body Leakage Current | $V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$ | - | - | ± 100 | nA |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$ | -0.4 | -0.7 | -1.0 | V |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=-4.5\text{V}$, $I_D=-4.1\text{A}$ | - | | 35 | m Ω |
| | | $V_{GS}=-2.5\text{V}$, $I_D=-3\text{A}$ | - | | 53 | |
| g_{FS} | Forward Transconductance | $V_{DS}=-5\text{V}$, $I_D=-15\text{A}$ | - | 6.6 | - | S |
| V_{SD} | Diode Forward Voltage | $I_S=-4.1\text{A}$, $V_{GS}=0\text{V}$ | - | -0.9 | -1.2 | V |
| DYNAMIC PARAMETERS ⁽⁵⁾ | | | | | | |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V}$, $V_{DS}=-10\text{V}$, $f=1\text{MHz}$ | - | 816 | - | pF |
| C_{oss} | Output Capacitance | | - | 84 | - | pF |
| C_{rss} | Reverse Transfer Capacitance | | - | 67 | - | pF |
| R_g | Gate Resistance | $V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$ | - | - | - | Ω |
| SWITCHING PARAMETERS ⁽⁵⁾ | | | | | | |
| Q_g | Total Gate Charge | $V_{GS}=-4.5\text{V}$, $V_{DS}=-10\text{V}$, $I_D=-2\text{A}$ | - | 8.9 | - | nC |
| Q_{gs} | Gate Source Charge | | - | 1.5 | - | nC |
| Q_{gd} | Gate Drain Charge | | - | 2.1 | - | nC |
| $t_{D(on)}$ | Turn-On Delay Time | $V_{GS}=-4.5\text{V}$, $V_{DS}=-10\text{V}$, $I_D=-3.3\text{A}$, $R_{GEN}=1\Omega$ | - | 11 | - | ns |
| t_r | Turn-On Rise Time | | - | 33 | - | ns |
| $t_{D(off)}$ | Turn-Off Delay Time | | - | 51 | - | ns |
| t_f | Turn-Off Fall Time | | - | 53 | - | ns |
| t_{rr} | Body Diode Reverse Recovery Time | $I_F=-10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$ | - | 23 | - | ns |
| Q_{rr} | Body Diode Reverse Recovery Charge | $I_F=-10\text{A}$, $di/dt=100\text{A}/\mu\text{s}$ | - | 11 | - | nC |

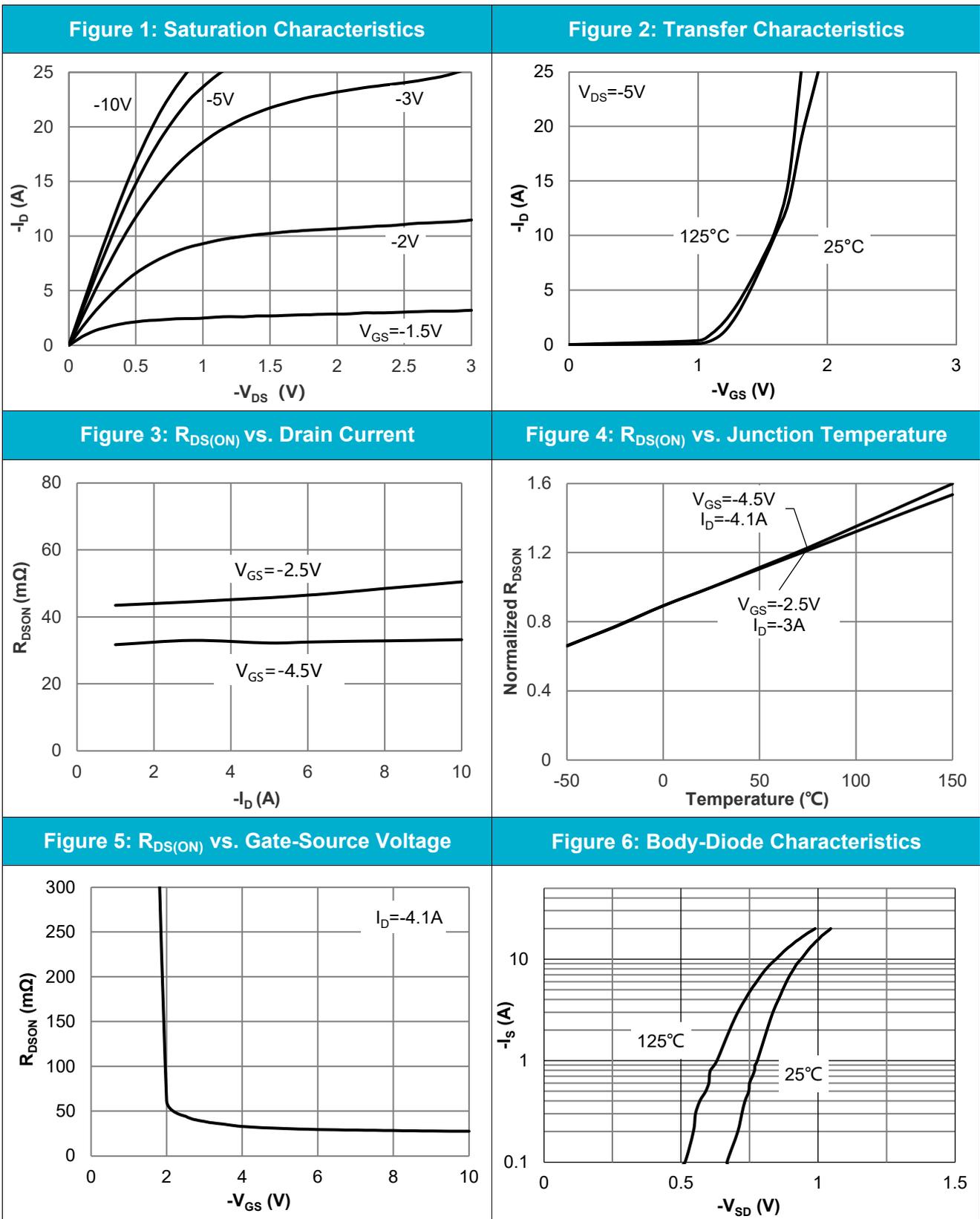
Thermal Resistances

| Symbol | Parameter | Typ | Max | Unit |
|-----------------|---|-----|-----|---------------------------|
| $R_{\theta JC}$ | Thermal resistance from junction to case | - | - | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal resistance from junction to ambient | - | 125 | $^\circ\text{C}/\text{W}$ |

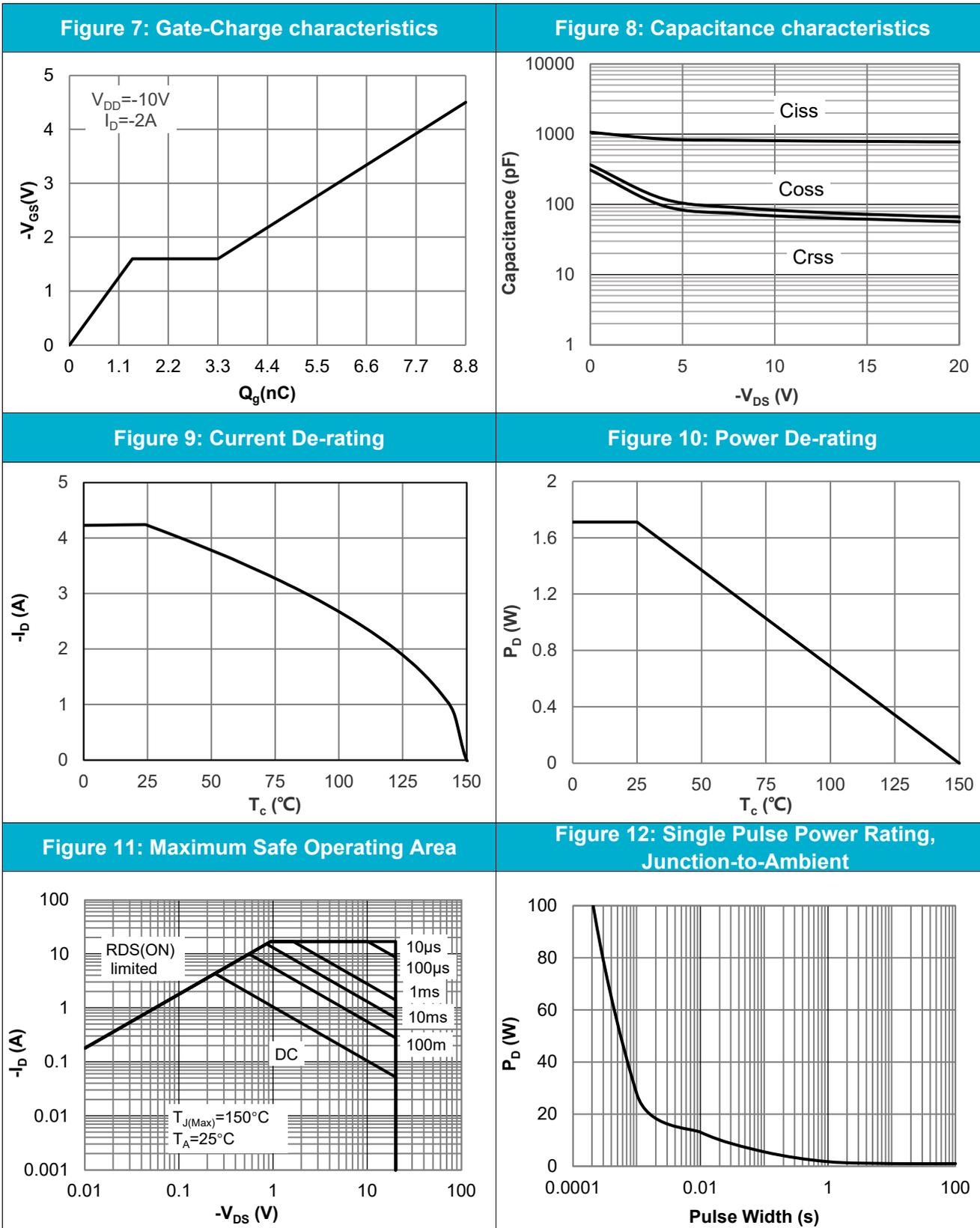
Notes:

1. Computed continuous current assumes the condition of T_{J_Max} while the actual continuous depends on the thermal & electro-mechanical application board design.
2. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
3. This single-pulse measurement was taken under the following condition [$L=0.1\text{mH}$, $V_{GS}=-10\text{V}$, $V_{DS}=-10\text{V}$] while its value is limited by $T_{J_Max}=150^\circ\text{C}$.
4. The power dissipation P_D is based on $T_{J_Max}=150^\circ\text{C}$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Electrical and Thermal Characteristics

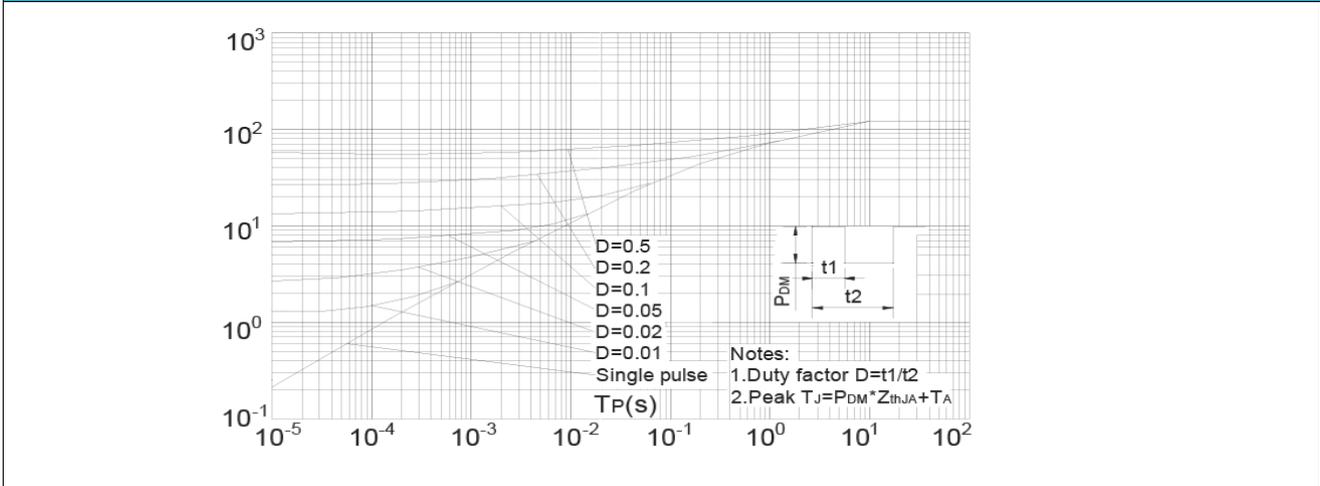


Typical Electrical and Thermal Characteristics



Typical Electrical and Thermal Characteristics

Figure 13: Normalized Maximum Transient Thermal Impedance



Test Circuit

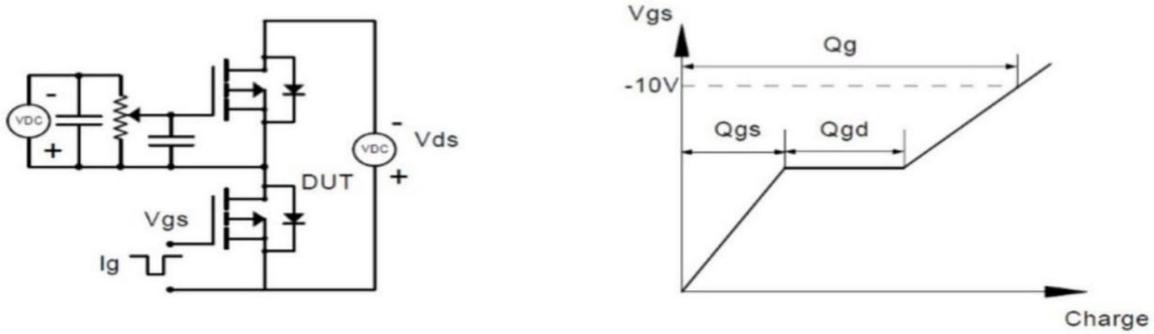


Figure1: Gate Charge Test Circuit & Waveforms

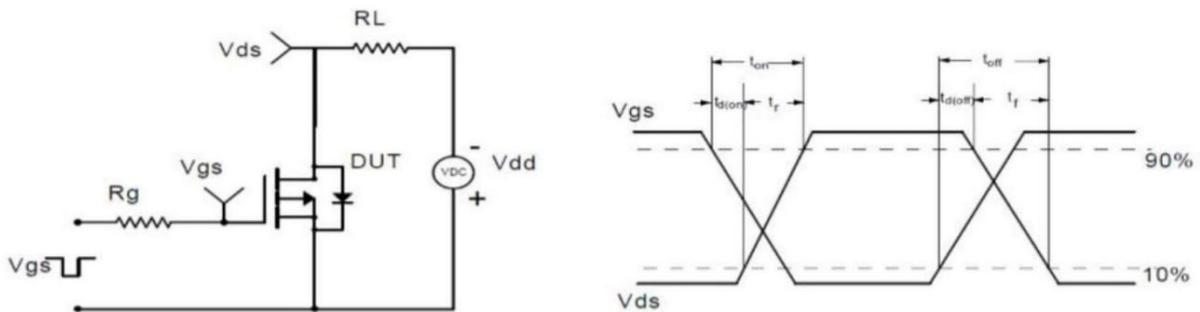


Figure2: Resistive Switching Test Circuit & Waveforms

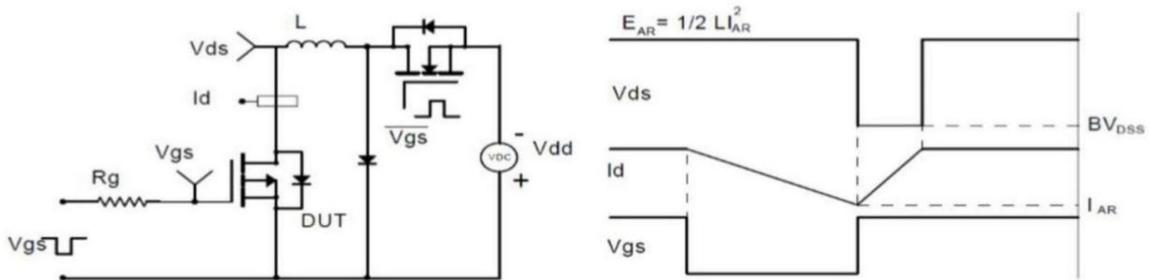


Figure3: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

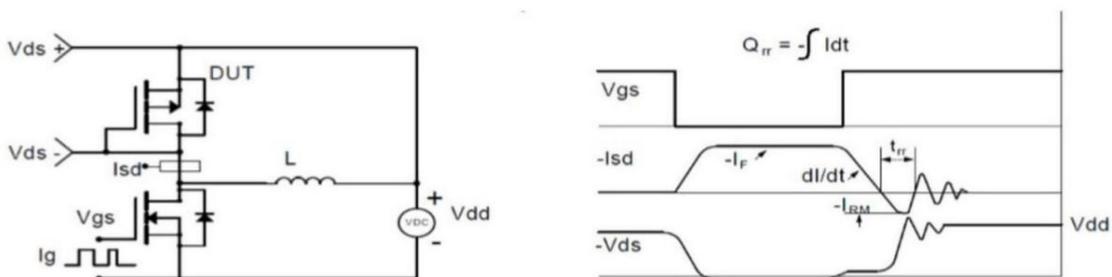
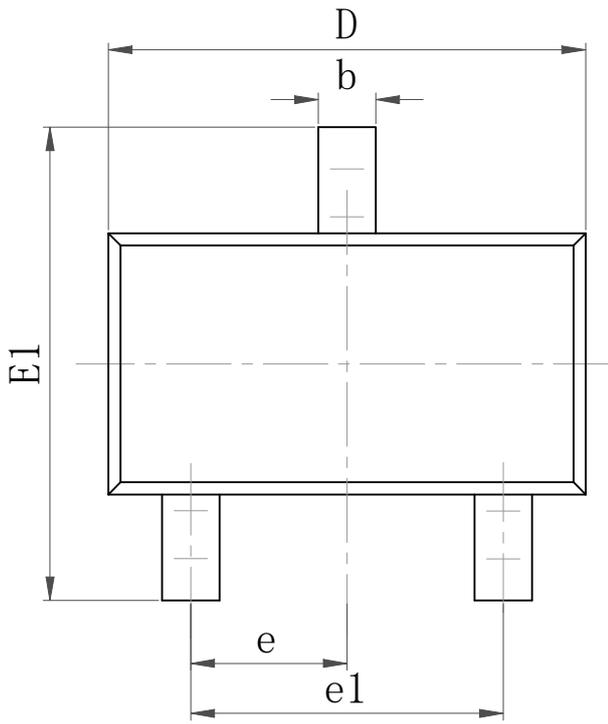
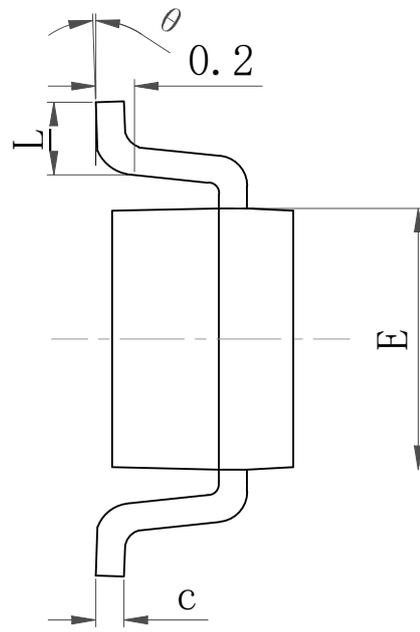


Figure4: Diode Recovery Test Circuit & Waveforms

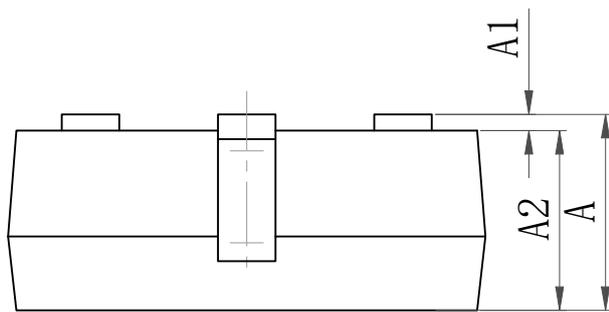
SOT-23 Package Information



TOP VIEW



SIDE VIEW



SIDE VIEW

| SYMBOL | MILLIMETER | |
|--------|-------------|-------|
| | MIN | MAX |
| A | 1.050 | 1.250 |
| A1 | 0.000 | 0.100 |
| A2 | 1.050 | 1.150 |
| b | 0.300 | 0.500 |
| c | 0.150 | 0.190 |
| D | 2.820 | 3.020 |
| E | 1.500 | 1.700 |
| E1 | 2.650 | 2.950 |
| e | 0.950 (BSC) | |
| e1 | 1.800 | 2.000 |
| L | 0.300 | 0.500 |
| θ | 0° | 8° |